

## Patent Abstracts of Japan

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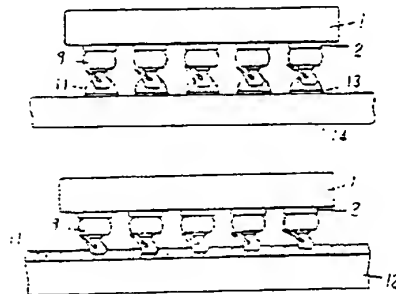
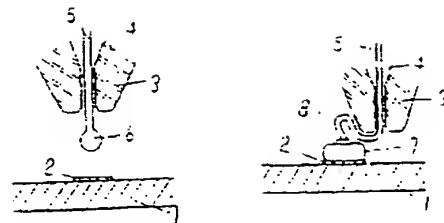
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 APPLICATION NUMBER : 63184936

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INVENTOR : ISHIDA TORU:

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TITLE : METHOD FOR MOUNTING  
 SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To mount a semiconductor device with high reliability by forming two-stage protrusion-shaped protrusion contacts at the electrode pads of the device, and electrically connecting the device to the conductor pattern of a substrate with a conductive adhesive having flexibility to be selectively transferred onto the protrusion contacts.

CONSTITUTION: After a ball formed by thermal energy at the end of a metal wiring 4 is press-bonded onto the electrode pad 2 of a semiconductor device 1 by means of a capillary 3, the wiring 4 is cut to form two-stage protrusion-shaped protrusion electrode 9. The contact 9 is flattened, and a conductive adhesive 11 is transferred only on the flattened contact 9 in coincidence with the adhesive face coating a supporting board 12 prepared separately. Then, after the device 1 is aligned on substrate 14 formed with a conductor pattern 13, the device 1 is secured onto the substrate 14 formed with the pattern 13 with the adhesive 11 on the contact 9. Thus, the device 1 can be electrically connected to the substrate 14 with high reliability.

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